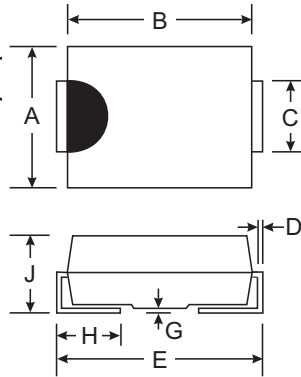


### Features

- Glass Passivated Die Construction
- Diffused Junction
- Ultra-Fast Recovery Time for High Efficiency
- Low Forward Voltage Drop, High Current Capability, and Low Power Loss
- Surge Overload Rating to 30A Peak
- Ideally Suited for Automated Assembly
- Available in Lead Free Finish/RoHS Compliant Version (Note 3)

### Mechanical Data

- Case: SMA
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Solder Plated Terminal - Solderable per MIL-STD-202, Method 208
- Also Available in Lead Free Plating (Matte Tin Finish). Please see Ordering Information, Note 5, on Page 1
- Polarity: Cathode Band or Cathode Notch
- Marking: Type Number & Date Code: See Below
- Ordering Information: See Below
- Weight: 0.064 grams (approximate)



SMA		
Dim	Min	Max
A	2.29	2.92
B	4.00	4.60
C	1.27	1.63
D	0.15	0.31
E	4.80	5.59
G	0.10	0.20
H	0.76	1.52
J	2.01	2.62
All Dimensions in mm		

### Maximum Ratings and Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

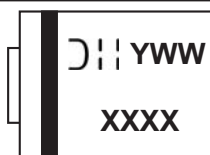
Characteristic	Symbol	US1A	US1B	US1D	US1G	US1J	US1K	US1M	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$V_{RRM}$ $V_{RWM}$ $V_R$	50	100	200	400	600	800	1000	V
RMS Reverse Voltage	$V_{R(RMS)}$	35	70	140	280	420	560	700	V
Average Rectified Output Current @ $T_T = 75^\circ\text{C}$	$I_O$	1.0							A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave Superimposed on Rated Load (JEDEC Method)	$I_{FSM}$	30							A
Forward Voltage Drop @ $I_F = 1.0\text{A}$	$V_{FM}$	1.0			1.3		1.7		V
Peak Reverse Current at Rated DC Blocking Voltage @ $T_A = 25^\circ\text{C}$ @ $T_A = 100^\circ\text{C}$	$I_{RM}$				5.0	100			$\mu\text{A}$
Reverse Recovery Time (Note 2)	$t_{rr}$	50					75		ns
Typical Junction Capacitance (Note 1)	$C_j$	20					10		pF
Typical Thermal Resistance, Junction to Terminal	$R_{\theta JT}$	30							$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range	$T_j, T_{STG}$	-65 to +150							$^\circ\text{C}$

### Ordering Information (Note 4)

Device*	Packaging	Shipping
US1x-13	SMA	5000/Tape & Reel

- Notes:
1. Measured with  $I_F = 0.5\text{A}$ ,  $I_R = 1.0\text{A}$ ,  $I_{rr} = 0.25\text{A}$ . See figure 5.
  2. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.
  3. Unit mounted on PC board with 5.0 mm<sup>2</sup> (0.013 mm thick) copper pad as heat sink.
  4. For Packaging Details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>. \*x = Device type, e.g. US1A-13.
  5. For Lead Free Finish/RoHS Compliant version part number, please add "-F" suffix to the part number above. Example: US1x-13-F.
  6. RoHS revision 13.2.2003. Glass and High Temperature Solder Exemptions Applied, see EU Directive Annex Notes 5 and 7.

### Marking Information



XXXX = Product type marking code, ex. US1A  
 JYW = Manufacturers' code marking  
 YWW = Date code marking  
 Y = Last digit of year ex: 2 for 2002  
 WW = Week code 01 to 52

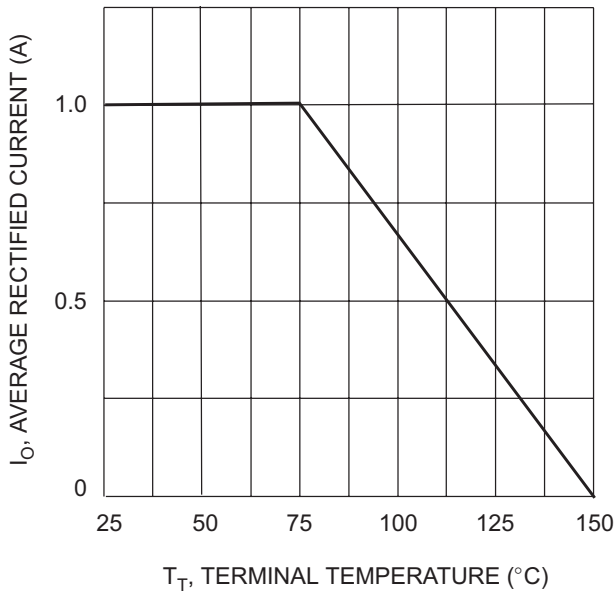


Fig. 1 Forward Current Derating Curve

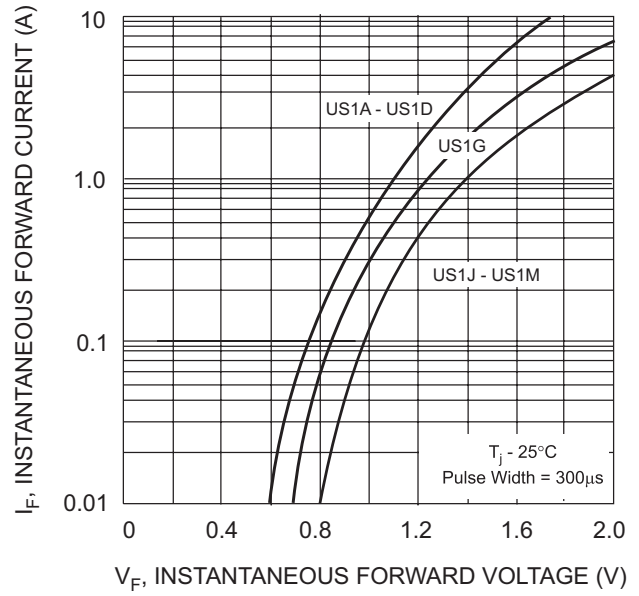


Fig. 2 Typical Forward Characteristics

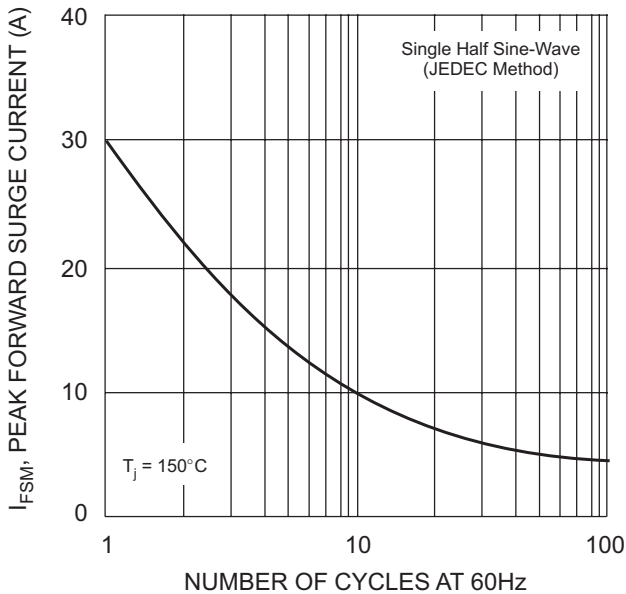


Fig. 3 Forward Surge Current Derating Curve

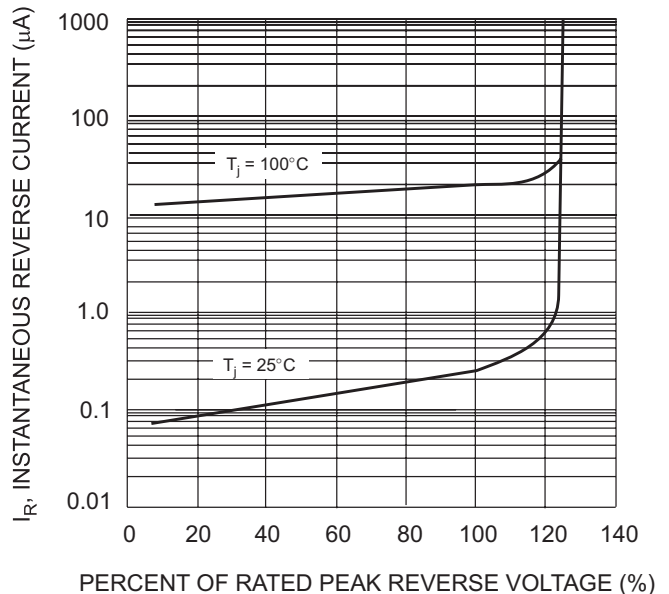
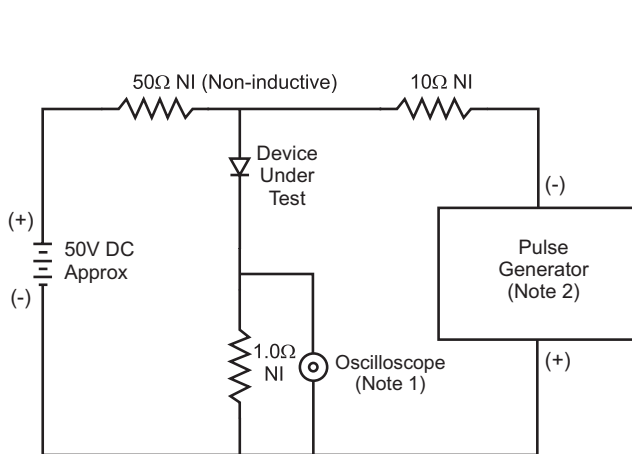
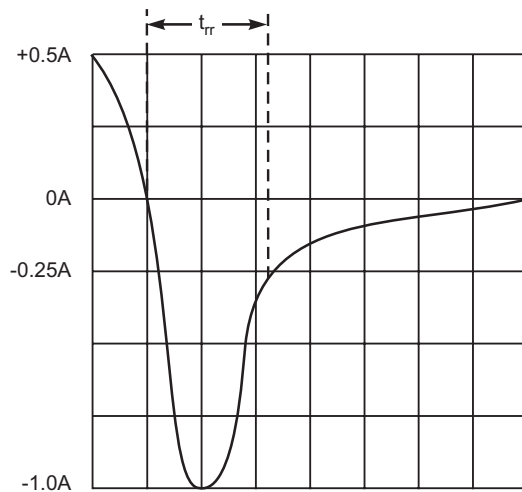


Fig. 4 Typical Reverse Characteristics



- Notes:
1. Rise Time = 7.0ns max. Input Impedance = 1.0MΩ, 22pF.
  2. Rise Time = 10ns max. Input Impedance = 50Ω.



Set time base for 50/100 ns/cm

Fig. 5 Reverse Recovery Time Characteristic and Test Circuit